

**IN THE CLAIMS:**

1.-42. (Canceled)

43. (Currently Amended) A method of inspecting a patterned wafer, comprising:  
emitting light containing a plurality of wavelengths from a light source;  
illuminating the patterned wafer with the light through a lens;  
detecting through the lens with a sensor, an image of a pattern on the patterned wafer as illuminated by the light, and outputting from the sensor, a signal concerning a detected image; and

processing the signal outputted from the sensor and obtaining information of defects of the pattern;

wherein light components having a predetermined wavelength range as are selected from the light emitted from the light source <sup>SUBSTANTIALLY</sup> for preventing interference of ~~lights reflected from the wafer by the illuminating, and~~ <sup>THE LIGHT COMPONENTS</sup> are used to illuminate the patterned wafer.

44. (Previously Presented) A method according to the Claim 43, wherein in the detecting, the image of the pattern is detected by a time delay integration sensor.

45. (Previously Presented) A method according to the Claim 43, wherein in the illuminating, the patterned wafer is illuminated with ultra violet light selected from the light emitted from the light source.

43. (Currently Amended) A method of inspecting a patterned wafer, comprising:

emitting light containing a plurality of wavelengths from a light source;

illuminating the patterned wafer with the light through a lens;

detecting through the lens with a sensor, an image of a pattern on the patterned wafer as illuminated by the light, and outputting from the sensor, a signal concerning a detected image; and

processing the signal outputted from the sensor and obtaining information of defects of the pattern;

wherein light components having a predetermined wavelength range as are selected from the light emitted from the light source to avoid substantial variation of the reflected light from the wafer, and the light components are used to illuminate the patterned wafer.

43. (Currently Amended) A method of inspecting a patterned wafer, comprising:

emitting light containing a plurality of wavelengths from a light source;

illuminating the patterned wafer with the light through a lens;

detecting through the lens with a sensor, an image of a pattern on the patterned wafer as illuminated by the light, and outputting from the sensor, a signal concerning a detected image; and

processing the signal outputted from the sensor and obtaining information of defects of the pattern;

wherein light components having a predetermined wavelength range as are selected from the light emitted from the light source to substantially maintain a constant reflectance level from the wafer, and the light components are used to illuminate the patterned wafer.